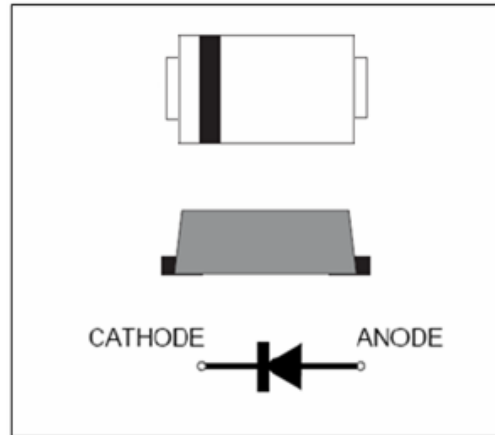


SODF101-SH thru SODF107-SH

Surface Mount Glass Passivated Junction Fast Recovery Rectifiers
Reverse Voltage 50 to 1000V Forward Current 1.0A

FEATURES

- * Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- * High temperature metallurgically bonded construction
- * Cavity-free glass passivated junction
- * Capable of meeting environmental standards of MIL-S-19500
- * Typical IR less than 1.0 μ A
- * High temperature soldering guaranteed: 260°C/10 seconds



We declare that the material of product is Halogen free (green epoxy compound)

Mechanical Data

Case: JEDEC SOD123-FL/MINI SMA, molded plastic over glass DIE

Terminals: Plated leads, solderable per MIL-STD-750, Method 2026

Polarity: Color band denotes cathode end

Mounting Position Any

Weight: 0.0155 g

Handling precaution: None

Electrical Characteristic

1. Maximum & Thermal Characteristics Ratings at 25°C ambient temperature unless otherwise specified.

| Parameter Symbol | symbol | SOD F101-SH | SOD F102-SH | SOD F103-SH | SOD F104-SH | SOD F105-SH | SOD F106-SH | SOD F107-SH | Unit |
|--|-----------------|-------------|-------------|-------------|-------------|-------------|-------------|-------------|---------------------------|
| Device marking code | | F1 | F2 | F3 | F4 | F5 | F6 | F7 | |
| Maximum repetitive peak reverse voltage | V_{RRM} | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| Maximum RMS voltage | V_{RMS} | 35 | 70 | 140 | 280 | 420 | 560 | 700 | V |
| Maximum DC blocking voltage | V_{DC} | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| Maximum average forward rectified current lead length at $T_C = 75^\circ\text{C}$ (Note 2) | $I_{F(AV)}$ | 1.0 | | | | | | | A |
| Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method) | I_{FSM} | 30 | | | | | | | A |
| Typical reverse recovery time (Note 1) | trr | 150 | | | | 250 | 500 | | ns |
| Typical thermal resistance (Note 2) | $R_{\theta JA}$ | 75 | | | | | | | $^\circ\text{C}/\text{W}$ |
| Operating junction temperature range | T_J | -55 to +150 | | | | | | | $^\circ\text{C}$ |
| storage temperature range | T_{STG} | -65 to +175 | | | | | | | $^\circ\text{C}$ |

Electrical Characteristics Ratings at 25°C ambient temperature unless otherwise specified.

| Parameter Symbol | symbol | SOD F101-SH | SOD F102-SH | SOD F103-SH | SOD F104-SH | SOD F105-SH | SOD F106-SH | SOD F107-SH | Unit |
|--|--------|-------------|-------------|-------------|-------------|-------------|-------------|-------------|---------------|
| Maximum instantaneous forward voltage at 1.0A | V_F | 1.3 | | | | | | | V |
| Maximum DC reverse current $T_J = 25^\circ\text{C}$ at rated DC blocking voltage $T_J = 125^\circ\text{C}$ | I_R | 5.0 100 | | | | | | | μA |
| Typical junction capacitance at 4.0V, 1MHz (Note 2) | C_J | 15.0 | | | | | | | PF |

NOTES:

1. $I_F = 0.5\text{A}$, $I_R = 1.0\text{A}$, $I_{RR} = 0.25\text{A}$

2. 8.0mm^2 (.013mm thick) land areas

SODF101-SH thru SODF107-SH

2. Characteristic Curves (TA = 25°C unless otherwise noted)

Fig. 1 - Forward Current Derating Curve

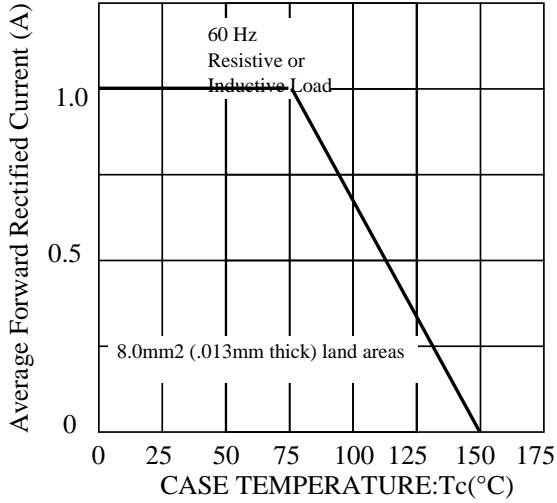


Fig. 2 - Maximum Non-repetitive Peak Forward Surge Current

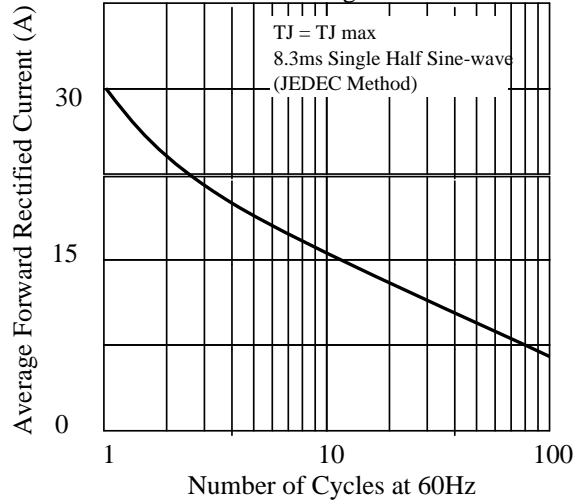


Fig. 3 - Typical Instantaneous Forward Characteristics

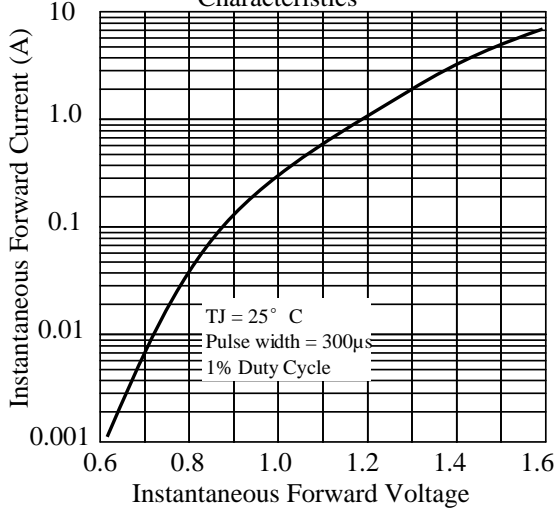


Fig. 4 - Typical Reverse Characteristics

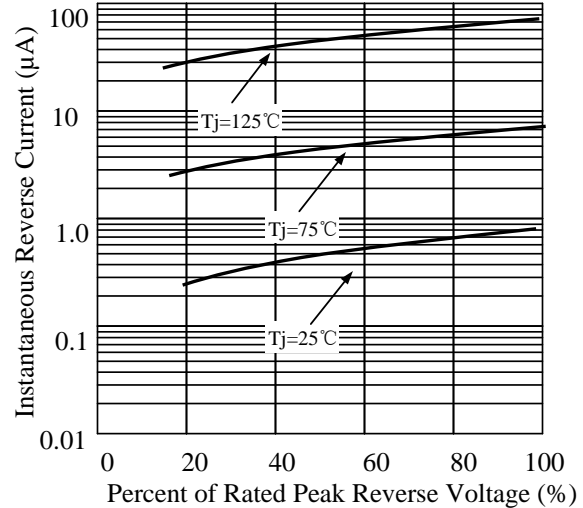


Fig. 5 - typical transient thermal impedance

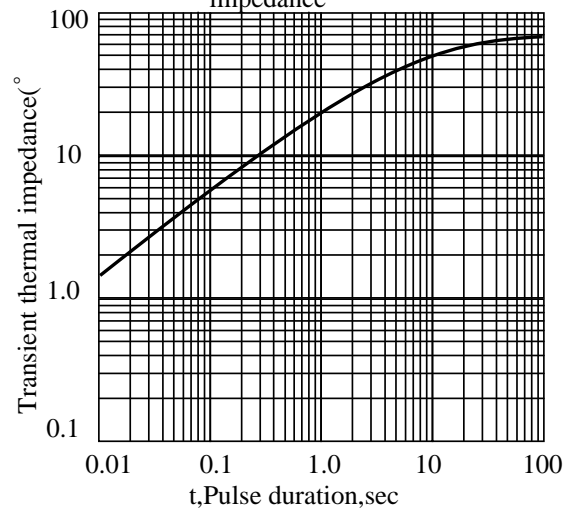
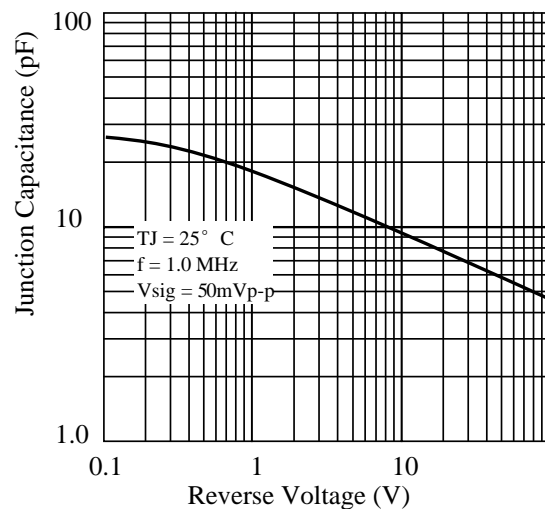


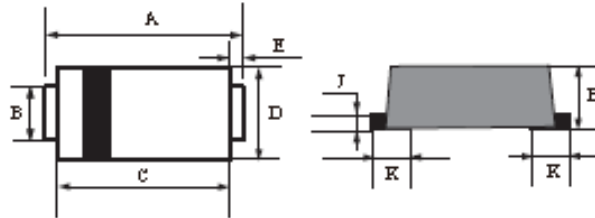
Fig. 6 - Typical Junction Capacitance



SODF101-SH thru SODF107-SH

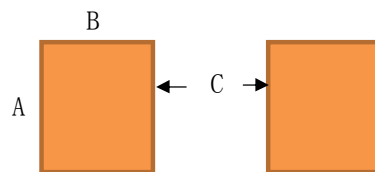
3. dimension:

SOD123-FL



| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|------|----------|-------|
| | MIN | MAX | MIN | MAX |
| A | 3.5 | 3.9 | 0.138 | 0.159 |
| B | 0.75 | 0.95 | 0.029 | 0.037 |
| C | 2.6 | 3.0 | 0.103 | 0.119 |
| D | 1.6 | 2.0 | 0.063 | 0.079 |
| E | 0.45Typ | | 0.018Typ | |
| H | 0.9 | 1.2 | 0.036 | 0.047 |
| J | 0.12 | 0.22 | 0.005 | 0.009 |
| K | 0.8Typ | | 0.032Typ | |

Suggested solder pad layout



Dimensions in inches and (millimeters)

| PACKAGE | A | B | C |
|-----------|-------------|-------------|-------------|
| SOD123-FL | 0.044(1.10) | 0.040(1.00) | 0.079(2.00) |

5.1 、 SMD Packing Reel Spec & Packing Quantity

5.1.1 Reel Packing

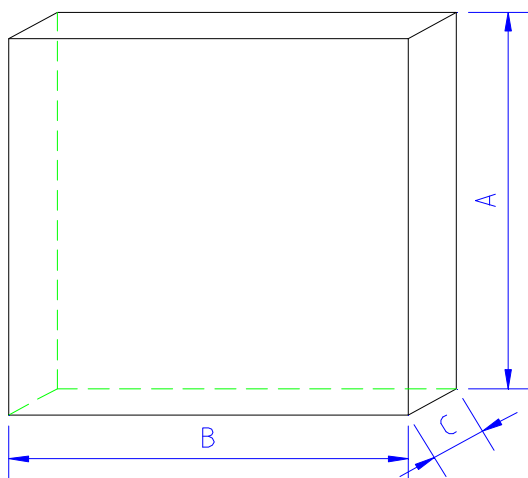
A. Reel Spec



unit: mm

| SPEC | A | B | C | W | Quantity/Reel |
|------------------|-----------|----------|----------|----------|---------------|
| SMA 7" reel | 177.0±2.0 | 54.0±0.5 | 13.0±0.5 | 13.2±0.2 | 2K |
| SMA13" reel | 330.0±2.0 | 75.0±0.5 | 13.0±0.5 | 13.2±0.2 | 5K |
| SMA-FL13" reel | 330.0±2.0 | 75.0±0.5 | 13.0±0.5 | 13.2±0.2 | 5K |
| TO277 13" reel | 330.0±2.0 | 75.0±0.5 | 13.0±0.5 | 13.2±0.2 | 5K |
| SOD123FL 7" reel | 177.0±2.0 | 50.0±0.5 | 13.0±0.5 | 9.4±1.5 | 3K |
| SOD323HE 7" reel | 177.0±2.0 | 50.0±0.5 | 13.0±0.5 | 9.4±1.5 | 3K |
| SMB-FL 13" reel | 330.0±2.0 | 75.0±0.5 | 13.0±0.5 | 13.2±0.2 | 5K |

B. 13" reel packing box



unit: mm

| size | A | B | C |
|------|---------|---------|--------|
| | 335±5.0 | 335±2.0 | 40±1.0 |

as per above packing

| Spec | Q' ty/Box |
|-----------------|-----------|
| SMA13" reel | 10K |
| TO277 13" reel | 10K |
| SMB-FL 13" reel | 10K |

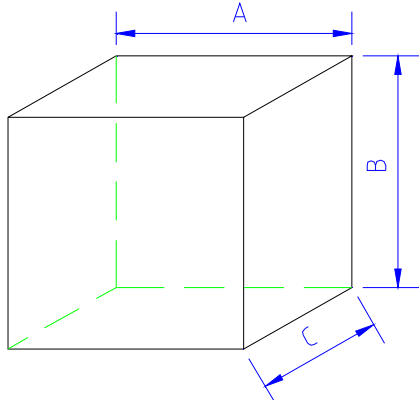
Title:
Power Diode SMD Package Packing Spec

DOC NO.: WI-258

DOC NO.: WI-258

Page: 3

C. 7" reel packing box



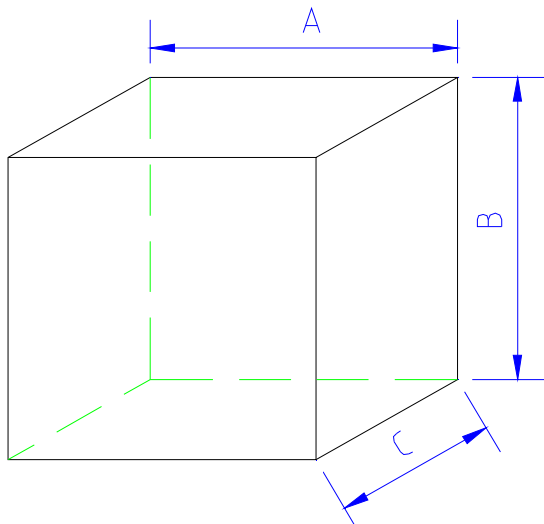
unit: mm

| | A | B | C |
|----------------------|---------|---------|---------|
| SMA/SMA-FL | 188±2.0 | 188±2.0 | 138±2.0 |
| SOD123FL SOD323HE | 186±2.0 | 139±2.0 | 185±2.0 |

as per above packing

| | Q' ty/Box |
|------------|-----------|
| SMA/SMA-FL | 16K |
| SOD123FL | 30K |
| SOD323HE | 30K |

D. reel packing carton



unit: mm

| | A | B | C |
|------|---------|---------|---------|
| size | 350±2.0 | 340±2.0 | 350±2.0 |

as per above packing

| Spec | Q' ty/Carton |
|--------------------|--------------|
| SMA/SMA-FL 7" reel | 80K |
| SMA13"reel | 80K |
| SMA-FL13"reel | 80K |
| TO277 13" reel | 80K |
| SMB-FL 13" reel | 80K |

unit: mm

| | A | B | C |
|----------------------|---------|---------|---------|
| SOD123FL SOD323HE | 455±2.0 | 400±2.0 | 410±2.0 |

as per above packing

| Spec | Q' ty/Carton |
|-------------------|--------------|
| SOD123-FL 7" reel | 360K |
| SOD323HE 7" reel | 360K |

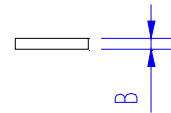
5.1.2 Tape Spec

A. Cover Tape



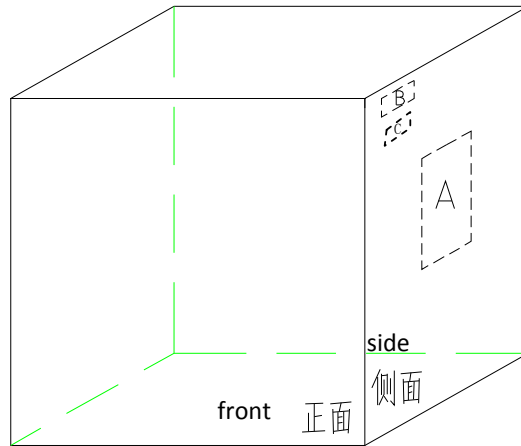
unit: mm

| | A | B |
|------------------------------------|----------|-------------|
| SMA /SMA-FL SMB-FL /TO277 | 9.5±0.10 | 0.062±0.007 |
| SOD123FL SOD323HE | 5.4±0.10 | |



5.2、SMD Power Diode General Packing Spec

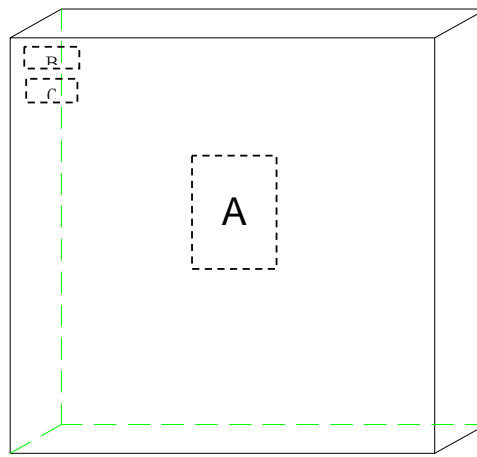
A. 7" reel all labels will be at cathode side of reel ;



A:LRC label;

B:Environment Label C:Halide free label

B. 13" reel



A:LRC label;

B:Environment Labe C:Halide free label

C. Tape lead: face anode side of the reel, upper side is the tape lead position. All labels are at cathode side of the reel.



标题:

Power Diode SMD Package Packing Spec

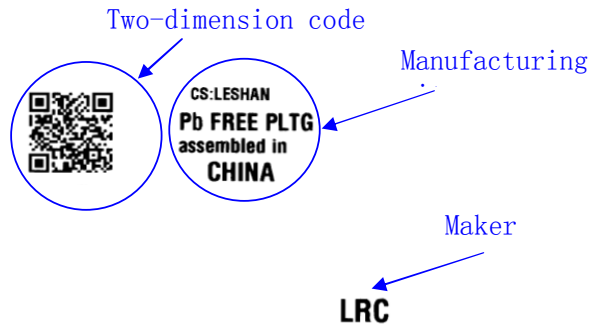
DOC NO.: WI-258

Version: 5 Modification: 0

Page: 6

C. Label Content :
LRC Label

P/N → (1P) LPN: SM140A
Lot No. → (1T) LOT: 140106049X
Date code → (9D) DTE: 1403
Quantity → (Q) QTY: 10000



lot: 140106049X: 140106---2014/1/6; 049----lot number:49; X: product code

Environment Label



Halide-free Label



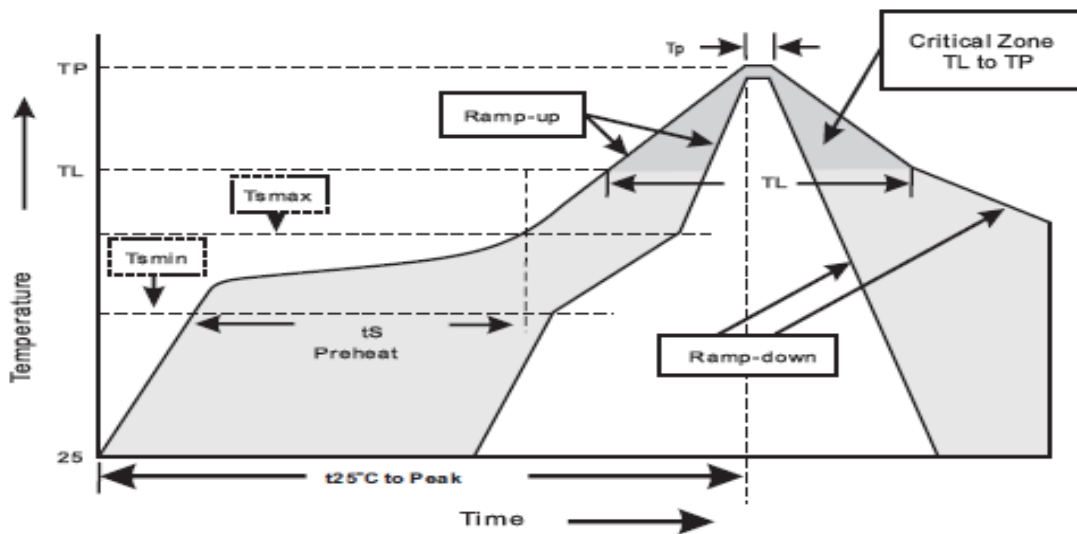
SODF101-SH thru SODF107-SH

Reel packing

| PACKAGE | REEL SIZE | REEL (PCS) | COMPONENT SPACING (mm) | BOX (pcs) | INNER BOX (mm) | REEL DIA. (mm) | CARTON SIZE (mm) | CARTON (PCS) | APPROX. GROSS WEIGHT (kg) |
|-----------|-----------|------------|------------------------|-----------|----------------|----------------|------------------|--------------|---------------------------|
| SOD123-FL | 7" | 3,000 | 4.0 | 30,000 | 183*183*123 | 178 | 382*262*387 | 240,000 | 8.7 |

5.Suggested thermal profile for soldering process

1. Storage environment : Temperature=5~40°C Humidity=55±25%
2. Reflow soldering of surface-mount device



3. Reflow soldering

| Profile Feature | Soldering Condition |
|---|---------------------|
| Average ramp-up rate(T _L to T _P) | <3°C/sec |
| Preheat | |
| - Temperature Min(T _{smin}) | 150°C |
| - Temperature Max(T _{smax}) | 200°C |
| - Time(min to max)(t _s) | 60~120sec |
| T _{smax} to T _L | |
| - Ramp-up Rate | <3sec |
| Time maintained above: | |
| - Temperature (T _L) | 217°C |
| - Time(t _L) | 60-260sec |
| Peak Temperature(T _P) | 255 -0/+5°C |
| Time within 5°C of actual Peak Temperature(T _P) | 10~30sec |
| Ramp-down Rate | <6°C/sec |
| Time 25°C to Peak Temperature | <6minutes |

SODF101-SH thru SODF107-SH

6.High reliability test capabilities

| Item Test | Condition | Reference |
|-------------------------------|--|----------------------------|
| Solder Resistance | at 260±5°C for 10±2sec immerse body into solder 1/16" ± 1/32" | MIL-STD-750D METHOD-2031 |
| Solderability | at 245±5°C for 5 sec | MIL-STD-202F METHOD-208 |
| High Temperature Reverse Bias | V _R =80% rate at T _J =150°C for 168hrs | MIL-STD-750D METHOD-1038 |
| Forward Operation Life | Rated average rectifier current T _A =25°C for 500hrs | MIL-STD-750D METHOD-1027 |
| Intermittent Operation Life | T _A =25°C , I _F =I _o On state:power on for 5 min. Off state:power off for 5 min. on and off for 500 cycles | MIL-STD-750D METHOD-1036 |
| Pressure Cooker | 15P _{SIG} at T _A =121°C for 4hrs | JESD22-A102 |
| Temperature Cycling | -55°C to +125°C dwelled for 30 min. and transferred for 5min. Total 10 cycles | MIL-STD-750D METHOD-1051 |
| Thermal Shock | 0°C for 5min. Rise to 100°C for 5min. Total 10 cycles | MIL-STD-750D METHOD-1056 |
| Forward Surge | 8.3ms single half sine-wave superimposed on rated load,one surge | MIL-STD-750D METHOD-4066-2 |
| Humidity | at T _A =85°C , RH=85% for 1000hrs | MIL-STD-750D METHOD-1021 |
| High Temperature Storage Life | at 175°C for 1000hrs | MIL-STD-750D METHOD-1031 |

SODF101-SH thru SODF107-SH

7. Update Record

| 版次 | 更新记录 | 更新作者 | 更新日期 |
|----|---|------|------------|
| 1 | 第一版 | 周杰 | 2012.06.11 |
| 2 | 管体高度由0.8~1.0mm修正为0.8~1.2mm; 引脚厚度由0.18~0.22mm调整为0.12~0.22mm; | 周杰 | 2012.12.05 |
| 3 | 因为所有SOD123系列均为无卤塑料, 所以取消印字下划线 | 周杰 | 2013.01.04 |
| 4 | 将封装SOD-123S修正为SOD123-FL | 周杰 | 2013.03.20 |